

Claims

1. A leadframe-based housing for a surface-mountable electronic component, with a
5 leadframe having a front side and a back side and comprising at least two electrical
connector strips (2a, 2b), and an injection-molded or transfer-molded housing base body
(8a, 8b) made from an electrically insulating injection compound and comprising a front
portion disposed at the front side of said leadframe and a back wall disposed at the back
side of said leadframe,
10 characterized in that
said leadframe comprises at least one injection aperture (24) through which said housing
base body is injected onto said leadframe from a back side of said leadframe.
2. The housing as described in claim 1,
15 characterized in that
said injection aperture (24) is disposed in one of said electrical connector strips.
3. The housing as described in claim 1 or 2,
wherein said back wall has a thickness of less than
20 0.3 mm and more than 0 mm.
4. The housing as described in at least one of claims 1 to 3 for a radiation-emitting and/or
radiation-detecting component,
wherein said housing base body (8a, 8b) comprises in said front portion (8a) a recess for
25 receiving a radiation-emitting and/or radiation-detecting chip, said injection aperture (24)
being disposed in the region of a wall of said front portion delimiting said recess.
5. The housing as described in claim 4, wherein said recess is formed as a reflector.
- 30 6. A leadframe ribbon comprising at least one housing as described in one of claims 1 to 5.

7. An electronic component having a housing as described in at least one of claims 1 to 5, which comprises at least one chip (16).
8. The electronic component as described in claim 7,
5 wherein said at least one chip (16) is a radiation-emitting and/or radiation-detecting chip.
9. The electronic component as described in claim 7 or 8,
wherein said chip (16) is disposed on one of the two connector strips (2a) and is electrically
connected to the second connector strip (2b) by means of an electrical connecting line (17).
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10. The electronic component as described in claim 7 or 8, wherein said chip (16) is disposed
on a mounting area of said housing base body and is electrically connected to each of said
electrical connector strips (2a, 2b) by means of in each case one electrical connecting
line(17).
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11. The electronic component as described in claim 7 or 8, wherein said chip (16) is disposed
on a thermally well-conducting chip carrier leading through said housing base body to the
back side and is electrically connected to each of said electrical connector strips (2a, 2b) by
means of in each case one electrical connecting line (17).
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12. The electronic component as described in at least one of claims 8 to 11, comprising a
housing with reference to claim 4 or 5,
wherein said recess is filled with an injection compound that is transparent to radiation
emitted by and/or to be detected by said chip.
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13. A method for producing a leadframe-based housing as described in one of claims 1 to 5,
comprising the following method steps:
 - a) preparing said leadframe comprising said two connector strips and said injection aperture
(24),
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 - b) applying to said leadframe an injection mold that forms around said leadframe a cavity for
creating said housing base body and inserting an injection nozzle into or placing it against
said injection aperture (24),

- c) injecting the injection compound into said cavity,
- d) at least partially solidifying the injection compound, and
- e) opening the injection mold, including the removal of said injection nozzle.

- 5 14. The method as described in claim 13,
wherein a thermoplastic material is used as the injection compound.